SFP28 | XFP

TE Internal #: 2170435-1

XFP, Cage Assembly, Through Hole - Press-Fit Mount, 1 Port, 1 x 1, Data Rate (Max) 10 Gb/s, Cable-to-Board, Sealable, Printed Circuit

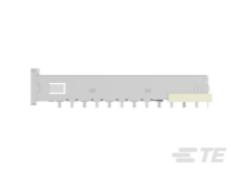
Board, XFP

View on TE.com >



Connectors > Pluggable IO Connectors & Cages > XFP > XFP Cage Assemblies and Kits











Pluggable I/O Product Type: Cage Assembly
PCB Mounting Style: Through Hole - Press-Fit

Number of Ports: 1

Port Matrix Configuration: 1x1

Data Rate (Max): 10 Gb/s

All XFP Cage Assemblies and Kits (22)

Features

Product Type Features

Form Factor	XFP
Cage Type	Single
Pluggable I/O Product Type	Cage Assembly
Connector System	Cable-to-Board
Sealable	Yes
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Ports	1
Port Matrix Configuration	1 x 1
Electrical Characteristics	
Data Rate (Max)	10 Gb/s

Body Features



Cage Plating Material	Tin
Termination Features	
Termination Post & Tail Length	2.05 mm[.08 in]
Termination Method to Printed Circuit Board	Through Hole - Press-Fit
Mechanical Attachment	
PCB Mounting Style	Through Hole - Press-Fit
Connector Mounting Type	Board Mount
Housing Features	
Cage Material	Copper Alloy
Dimensions	
Product Width	65.53 mm[2.57 in]
Product Length	21.7 mm[.854 in]
Usage Conditions	
Operating Temperature Range	-10 – 70 °C[-14 – 158 °F]
Operation/Application	
Heat Sink Application	Yes
Heat Sink Compatible	No
For Use With Pluggable I/O Products	XFP Connector / XFP Cable Plug
Circuit Application	Signal
Packaging Features	
Packaging Method	Tray
Other	
Included Lightpipe	No

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2022 (223)



Does not contain R	REACH SVHO	
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Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Not applicable for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts

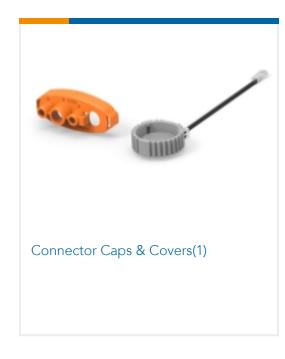








Also in the Series | XFP







Customers Also Bought



















Documents

Product Drawings

XFP CAGE ASSEMBLY

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2170435-1_A.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2170435-1_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2170435-1_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use

Product Specifications

Product Specification

English